| PCN Number:  |        |           | 20150123003 PCN Date: 1/26/2015 |   |                           |                          |        |  |  | 1/26/2015   |                   |                          |           |  |  |
|--|--------|-----------|---------------------------------|---|---------------------------|--------------------------|--------|--|--|-------------|-------------------|--------------------------|-----------|--|--|
| Title:Qualification<br>package   |        |           |                                 | ion of HIT as Additional Assembly/Test location for Select Devices in the DCU |                           |                          |        |  |  |             |                   |                          |           |  |  |
| Customer<br>Contact:   |        |           | PCN Manager                     |   |                           | Dept:                    |        | Quality Services   |  |             |                   |                          |           |  |  |
| Proposed 1 <sup>st</sup> Shij<br>Date:   |        |           | р                               | 04/26/2015  |                           |                          | Esti   | Estimated Sample Availability: Date provide upon request |  |             |                   |                          | -         |  |  |
| Cha  | nge '  | Туре:     |                                 |   |                           |                          |        |  |  |             |                   |                          |           |  |  |
| $\boxtimes$  | Ass    | embly Sit | e                               |   | Assembly Proces           |                          |        |  |  | $\boxtimes$ | _                 | Assembly Ma              | laterials |  |  |
|  | Design |           |                                 |   |                           | Electrical Specification |        |  |  |             |                   | Mechanical Specification |           |  |  |
| Test Site  |        |           |                                 |   | Packing/Shipping/Labeling |                          |        |  |  |             | Test Process      |                          |           |  |  |
| Wafer Bump Site  |        |           | Site                            |   |                           | Wafer Bump Material      |        |  |  |             |                   | Wafer Bump Process       |           |  |  |
| Wafer Fab Site   |        | te        |                                 |   | Wafer Fab Materials       |                          |        |  |  |             | Wafer Fab Process |                          |           |  |  |
|  |        |           |                                 |   | Part number change        |                          |        |  |  |             |                   |                          |           |  |  |
| PCN Details  |        |           |                                 |   |                           |                          |        |  |  |             |                   |                          |           |  |  |
| Des  | cript  | ion of Cł | nange                           | e:  |                           |                          |        |  |  |             |                   |                          |           |  |  |
| Texas Instruments is pleased to announce the qualification of Hitachi as an alternate Assembly and Test site for the devices listed below. Device construction differences are noted as follows: |        |           |                                 |   |                           |                          |        |  |  |             |                   |                          |           |  |  |
| N  |        |           | Wh                              | What  |                           |                          |        | Hana Thailand  |  |             |                   | Hitachi                  |           |  |  |
| Mo   |        |           | Μοι                             | Iount Compound  |                           |                          |        | SID#400154   |  |             | SID#RZ241         |                          |           |  |  |
|  |        |           | Mol                             | Mold Compound   |                           |                          |        | SID#450207   |  |             |                   | SID#RM500F               |           |  |  |
| Le   |        |           | Lea                             | d Fi  | ini                       | sh                       | NiPdAu |  |  | Matte Sn    |                   |                          |           |  |  |
|  |        |           |                                 |   |                           |                          |        |  |  |             |                   |                          |           |  |  |

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Upon expiry of this PCN TI will combine lead free solutions in a single <u>standard part number</u>, for example; <u>SN74AVCH2T45DCUR</u> – can ship with both Matte Sn and NiPdAu/Ag.

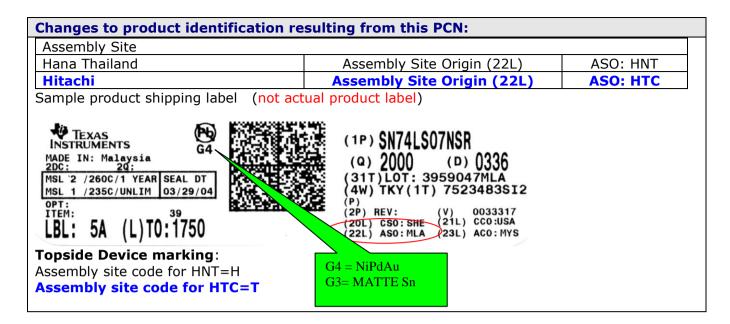
Example:

- Customer order for 7500units of SN74AVCH2T45DCUR with 2500 units SPQ (Standard Pack Quantity per Reel).
- TI can satisfy the above order in one of the following ways.
  - I. 3 Reels of NiPdAu finish.
  - II. 3 Reels of Matte Sn finish
  - III. 2 Reels of Matte Sn and 1 reel of NiPdAu finish.
  - IV. 2 Reels of NiPdAu and 1 reel of Matte Sn finish.

## **Reason for Change:**

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): None



| Product Affected |                  |              |              |              |  |  |  |  |  |  |
|------------------|------------------|--------------|--------------|--------------|--|--|--|--|--|--|
|                  | SN74AVCH2T45DCUR | TCA9406DCUR  | TS5A3359DCUT | TXB0102DCUT  |  |  |  |  |  |  |
|                  | SN74AVCH2T45DCUT | TS5A3359DCUR | TXB0102DCUR  | 1/1001020001 |  |  |  |  |  |  |

## Qualification Report

## A-T site Transfer: TXB0102DCUR, TCA9406DCUR, SN74AVCH2T45DCUR, and TS5A3359DCUR (HNT to HIT) Approved 01/13/2015

## Product Attributes

| Attributes          | Qual Device:<br>SN74AVCH2T45DCUR | Qual Device:<br>TCA9406DCUR | Qual Device:<br>T S5A3359DCUR | Qual Device:<br>TXB0102DCUR | QBS Package:<br>SN74LVC2G125DCUR | QBS Package:<br>SN74LVC2G74DCUR | QBS Package:<br>SN74CB3Q3306ADCUR |
|---------------------|----------------------------------|-----------------------------|-------------------------------|-----------------------------|----------------------------------|---------------------------------|-----------------------------------|
| Assembly Site       | HIT                              | HIT                         | HIT                           | HIT                         | HITACHI-RENESAS                  | HITACHI-RENESAS                 | HITACHI-RENESAS                   |
| Package Family      | -                                | -                           | -                             |                             | -                                | -                               | -                                 |
| Flammability Rating | -                                | -                           | -                             |                             | UL 94 V-0                        | UL 94 V-0                       | UL 94 V-0                         |
| Wafer Fab Site      | FFAB                             | FFAB                        | FFAB                          | FFAB                        | FFAB                             | FFAB                            | FFAB                              |
| Wafer Fab Process   | ASLC10/P9705                     | ASLC10/P9785                | ASLC10/P9785                  | ASLC10/P9785                | ASL3C                            | ASL3C                           | ACTPI                             |

GBS: Qual By Similarity
Cust Custor Control C

| Qualification Results  |
|--|
| Data Displayed as: Number of lots / Total sample size / Total failed |

| Туре | Test Name / Condition         | Duration                          | Qual Device:<br>SN74AVCH2T45DCUR | Qual Device:<br>TCA9406DCUR | Qual Device:<br>T S5A3359DCUR | Qual Device:<br>TXB0102DCUR | QBS Package:<br>SN74LVC2G125DCUR | QBS Package:<br>SN74LVC2G74DCUR | QBS Package:<br>SN74CB3Q3306ADCUR |
|------|-------------------------------|-----------------------------------|----------------------------------|-----------------------------|-------------------------------|-----------------------------|----------------------------------|---------------------------------|-----------------------------------|
| HAST | Biased HAST, 130C/85%RH       | 96 Hours                          | -                                | -                           | -                             | -                           | -                                | 3/231/0                         | -                                 |
| AC   | Autoclave 121C                | 96 Hours                          | -                                | -                           | -                             | -                           | -                                | -                               | -                                 |
|      | Unbiased HAST 130C/85%RH      | 96 Hours                          | -                                | -                           | -                             | -                           | -                                | 3/231/0                         | 3/231/0                           |
|      | Temperature Cycle, -65/150C   | 500 Cycles                        | -                                | -                           | -                             | -                           | -                                | 3/231/0                         | 3/231/0                           |
|      | High Temp. Storage Bake, 170C |                                   | -                                | -                           | -                             | -                           |                                  | 3/231/0                         | -                                 |
| HTSL | High Temp. Storage Bake, 175C | 500 Hours                         | -                                | -                           | -                             | -                           | -                                | -                               | -                                 |
|      | Thermal Shock-65/150C         | 500 Cycles                        | -                                | -                           | -                             | -                           | -                                | 3/231/0                         | -                                 |
|      | Life Test, 150C               | 300 Hours                         | -                                | -                           | -                             | -                           | -                                | 3/231/0                         | -                                 |
|      | Bond Shear                    | Wires                             | -                                | -                           | -                             | -                           | -                                | -                               | -                                 |
| WBP  | Bond Pull                     | Wires                             | -                                | -                           | -                             | -                           | -                                | -                               | -                                 |
| SD   | Solderability                 | Post 8 Hours Steam Age            | -                                | -                           | -                             | -                           | -                                | 3/66/0                          | -                                 |
| PD   | Physical Dimensions           |                                   | -                                | -                           | -                             | -                           | -                                | 3/15/0                          | -                                 |
| LI   | Lead Fatigue                  | Leads                             | -                                | -                           | -                             | -                           | -                                | 3/66/0                          | -                                 |
| LI   | Lead Pull                     | Leads                             | -                                | -                           | -                             | -                           | -                                | 3/66/0                          | -                                 |
| HBM  | ESD - HBM                     | 2000 V                            | -                                | -                           | -                             | -                           | -                                | -                               | -                                 |
| HBM  | ESD - HBM                     | 2500 V                            |                                  |                             |                               |                             |                                  |                                 |                                   |
| CDM  | ESD - CDM                     | 750 V                             | -                                | -                           | -                             | -                           | -                                | -                               | -                                 |
| CDM  | ESD - CDM                     | 1000 V                            |                                  |                             |                               |                             |                                  |                                 |                                   |
| CDM  | ESD – CDM                     | 1500 V                            |                                  |                             |                               |                             |                                  |                                 |                                   |
| LU   | Latch-up                      | (per JESD78)                      | -                                | -                           | -                             | -                           | -                                | -                               | -                                 |
| ED   | Auto Electrical Distributions | Cpk>1.67 Room, hot, and cold test | -                                | -                           | -                             | -                           |                                  | -                               | -                                 |
| ED   | Electrical Characterization   | Per Datasheet Parameters          | Pass                             | Pass                        | Pass                          | Pass                        | -                                | -                               | -                                 |
| WBS  | Bond Strength                 | Wires                             | -                                | -                           | -                             | -                           | -                                | 3/231/0                         | 3/231/0                           |
| FLAM | Flammability (IEC 695-2-2)    |                                   | -                                | -                           | -                             | -                           | -                                | 3/15/0                          | -                                 |
| FLAM | Flammability (UL 94V-0)       |                                   | -                                | -                           | -                             | -                           | -                                | 3/15/0                          | -                                 |
| FLAM | Flammability (UL-1694)        |                                   | -                                | -                           | -                             | -                           | -                                | 3/15/0                          | -                                 |

Preconditioning was performed for Autoclave. Unbiased HAST, THB/Biased HAST, Temparature Cycle. Thermal Shock, and HTSL, as applicable The following are equivalent HTOL options based on an activation energy of 0.74°. 125/C14.Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours. The following are equivalent TEmp Cycle options per JESD47<sup>-</sup>: 35C/125C/700 Cycles and 45C/150C/500 Cycles Justig and Environmental data is available at The settinal West Shock Hutp/Jww.Licom/

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location     | E-Mail                         |
|--------------|--------------------------------|
| USA          | PCNAmericasContact@list.ti.com |
| Europe       | PCNEuropeContact@list.ti.com   |
| Asia Pacific | PCNAsiaContact@list.ti.com     |
| Japan        | PCNJapanContact@list.ti.com    |